

Amendments to the Specification

Please replace paragraph [0067] with the following rewritten paragraph:

[0067] In step 8, as shown in Fig. 8, the microtile element 61 aligned with the predetermined position of the second substrate 71 is pressed through the intermediate transfer film 31 with a collet-back pressing pin 81 to be joined to the second substrate 71. Since the adhesive 73 is applied to the predetermined position, the microtile element 61 is bonded to the predetermined position of the second substrate 71. Although the adhesive is used to fix the microtile element 61 to the second substrate 71 in this step, any other fixing method may be used.

Please replace paragraph [0069] with the following rewritten paragraph:

[0069] As the adhesive for the intermediate transfer film 31, a UV cure or thermosetting adhesive is used. Immediately after step 6, the adhesion of the intermediate transfer film 31 is made ineffective entirely by irradiating the intermediate transfer film 31 entirely with ultraviolet light or the like. Even if the adhesion is made ineffective, in practice, a slight tackiness remains, and since the microtile element 61 is extremely thin and light, the microtile element 61 remains bonded to the intermediate transfer film 31. When a UV cure adhesive is used, by using a collet-back pressing pin 81 composed of a transparent material and applying (transmitting) ultraviolet (UV) light through the edge (bottom face) of the collet-back pressing pin 81, the adhesion of the intermediate transfer film 31 may be made ineffective. On the other hand, when a thermosetting adhesive is used, by heating the collet-back pressing pin 81, the adhesion of the intermediate transfer film 31 may be made ineffective.